

I. AMENDMENTS TO THE CLAIMS:

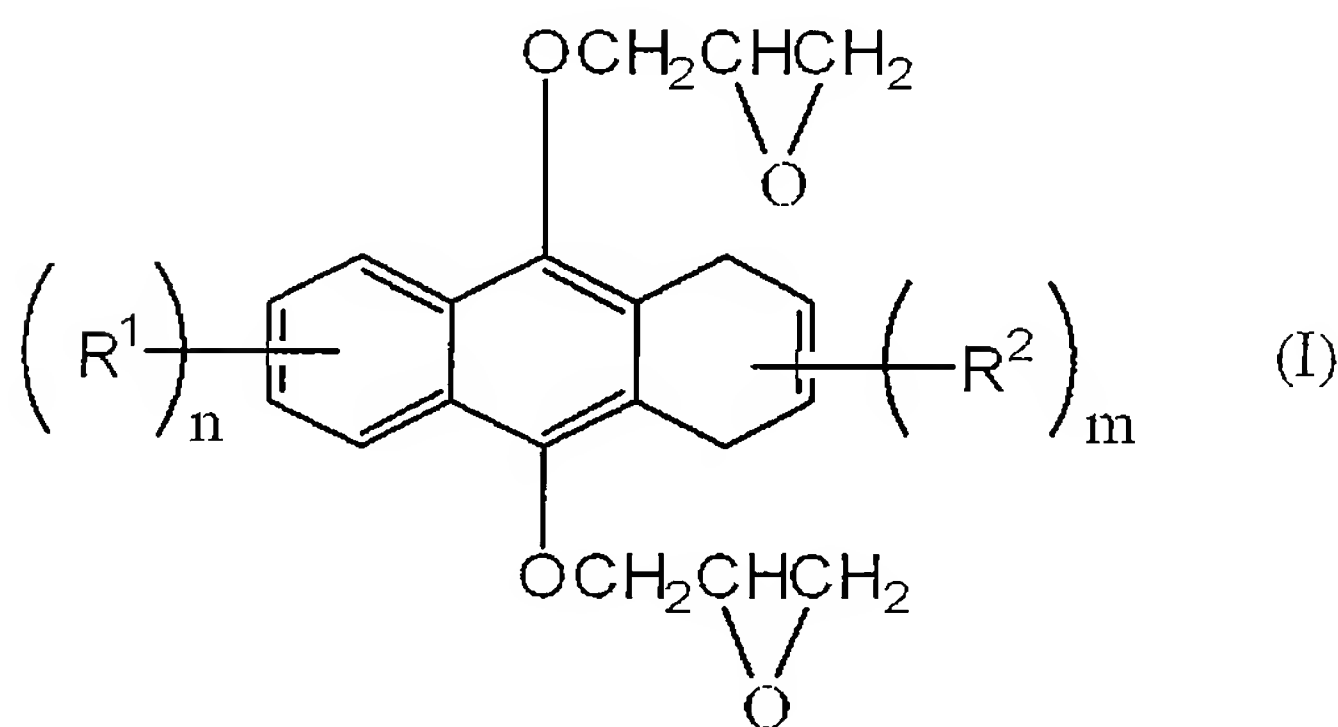
Kindly amend claims 1, 2, 11, 13, 14, 16-18, 21, 25 and 26 and as follows.

The following claims will replace all prior versions of claims in the present application.

Listing of Claims:

1. (Currently Amended) A sealant epoxy-resin molding material, comprising an epoxy resin (A) and a hardening agent (B), wherein the epoxy resin (A) contains a compound represented by the following General Formula (I):

—[Formula 1]



wherein (in General Formula (I), R¹ represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxyl groups having 1 to 12 carbon atoms, and the groups R¹ may be the same as, or different from, each other;

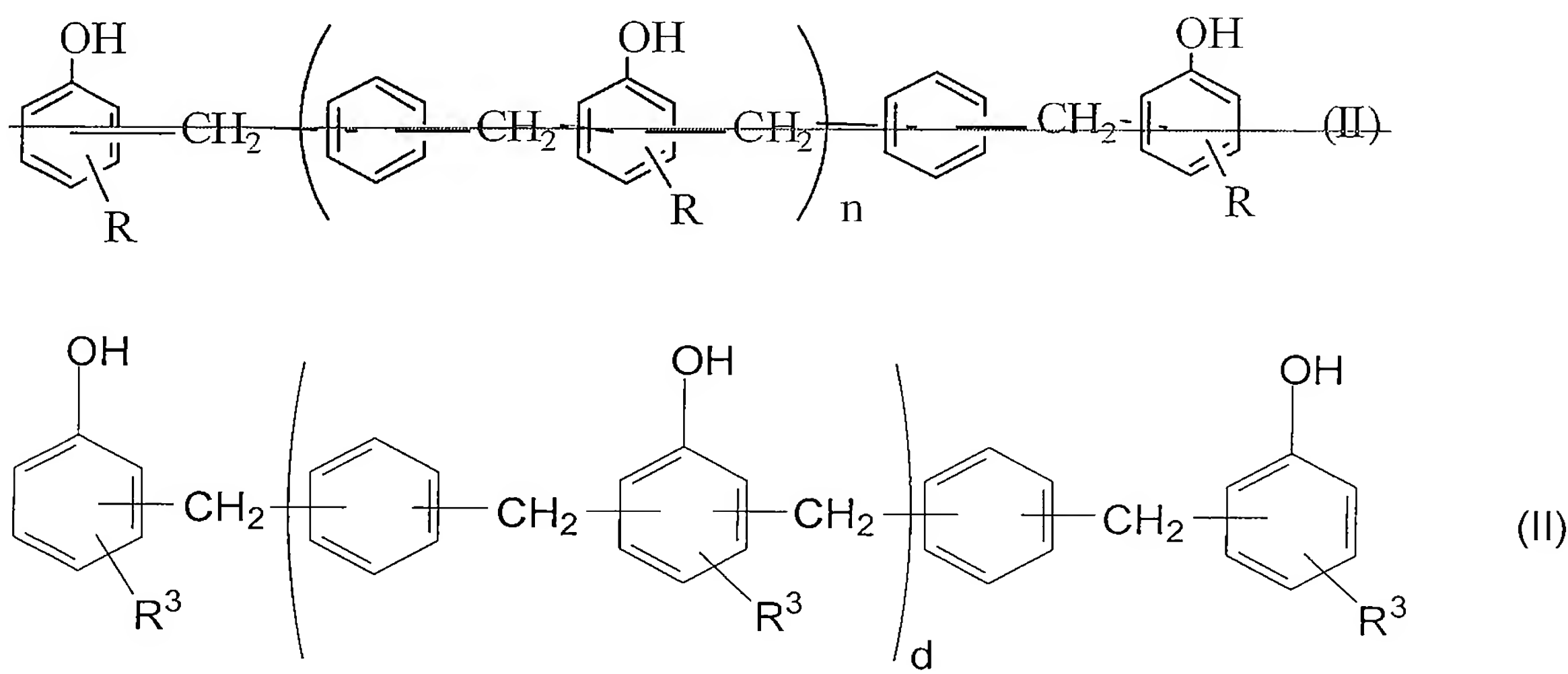
n is an integer of 0 to 4;

R² represents a ~~group~~ groups selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms, and the groups R² may be the same as, or different from, each other; and

m is an integer of 0 to 6).

2. (Currently Amended) The sealant epoxy-resin molding material according to Claim 1, wherein the hardening agent (B) contains a compound represented by the following General Formula (II):

—[Formula 2]—



(wherein, \underline{R} represents a group selected from a hydrogen atom and substituted or unsubstituted monovalent hydrocarbon groups having 1 to 10 carbon atoms; and \underline{n} is an integer of 0 to 10).

3. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising a hardening accelerator (C).

4. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is triphenylphosphine.

5. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is an adduct of a tertiary phosphine compound and a quinone compound.

6. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising an inorganic filler (D).

7. (Original) The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 60 to 95 wt % with respect to the sealant epoxy-resin molding material.

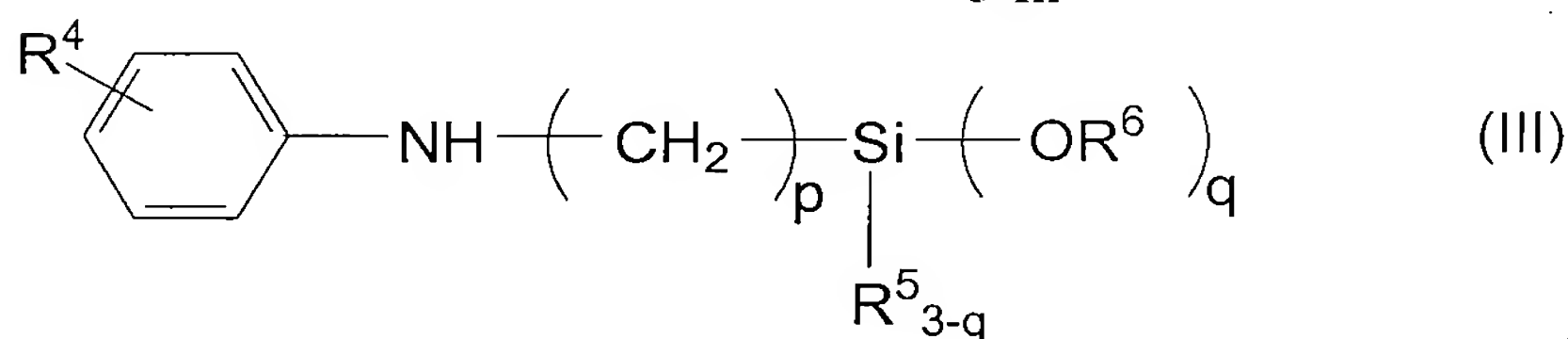
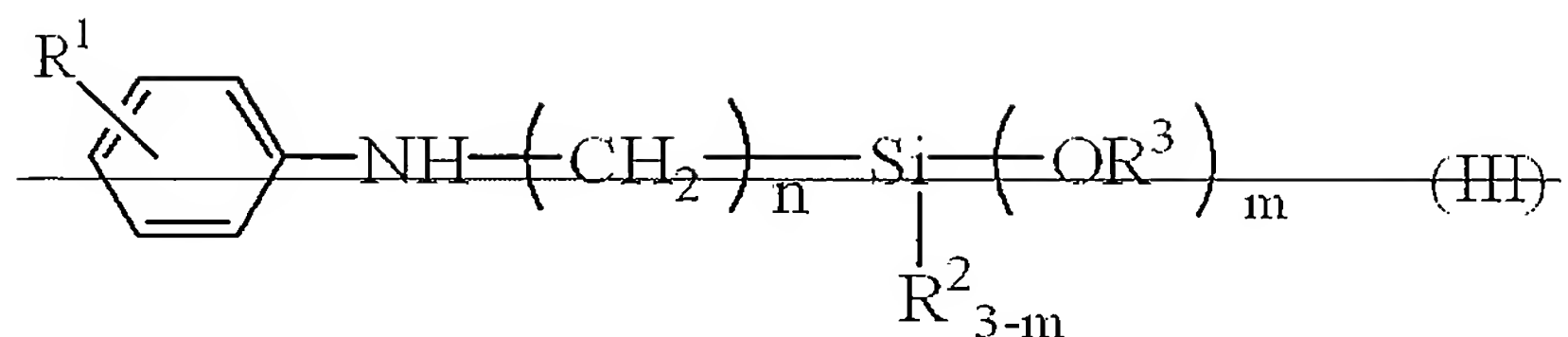
8. (Previously Presented) The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 70 to 90 wt % with respect to the sealant epoxy-resin molding material.

9. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising a coupling agent (E).

10. (Original) The sealant epoxy-resin molding material according to Claim 9, wherein the coupling agent (E) contains a secondary amino group-containing silane-coupling agent.

11. (Currently Amended) The sealant epoxy-resin molding material according to Claim 10, wherein the secondary amino group-containing silane-coupling agent contains a compound represented by the following General Formula (III):

[Formula 3]



(wherein, R^1 - R^4 represents a group selected from a hydrogen atom, alkyl groups having 1 to 6 carbon atoms, and alkoxy group having 1 to 2 carbon atoms;

R^5R^2 represents a group selected from alkyl groups having 1 to 6 carbon atoms and a phenyl group;

R^6R^3 represents a methyl or ethyl group;

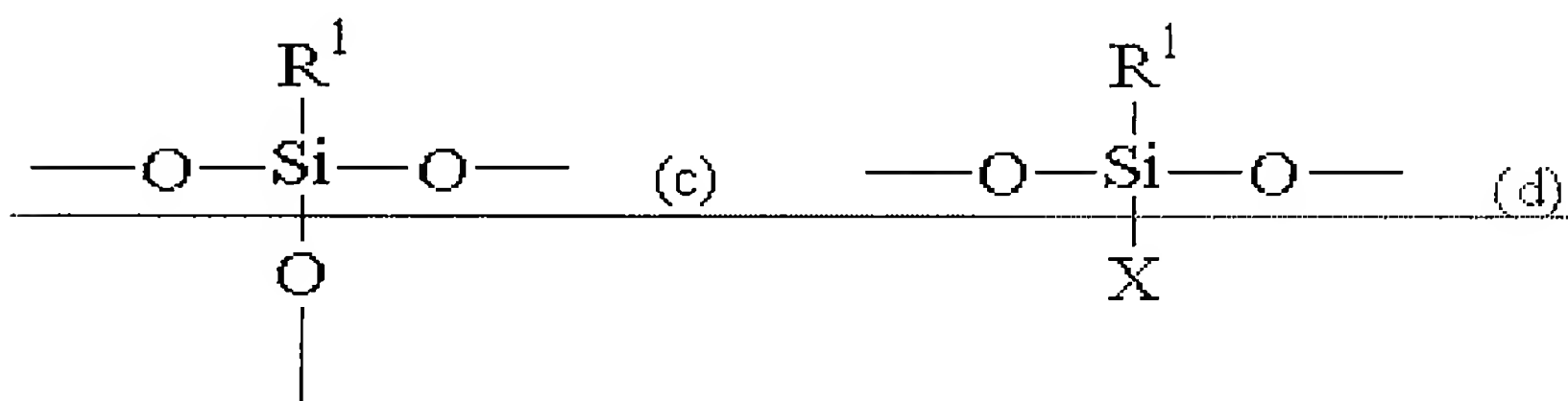
n is an integer of 1 to 6; and

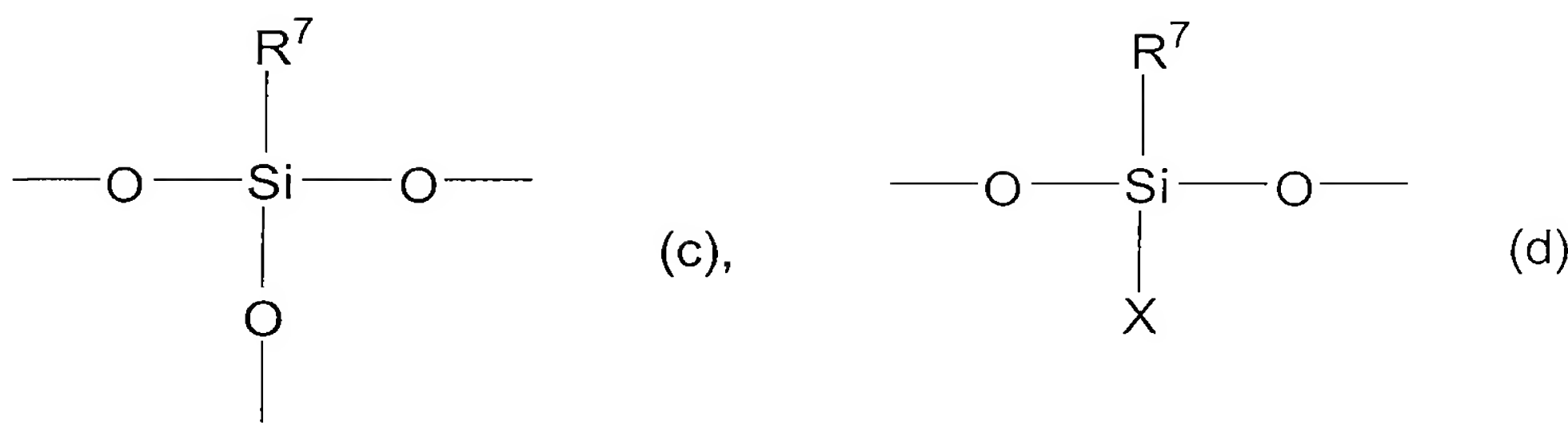
m is an integer of 1 to 3).

12. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

13. (Currently Amended) The sealant epoxy-resin molding material according to Claim 1, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), a terminal selected from R^1 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.

—[Formula 4]





a terminal selected from R^7 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

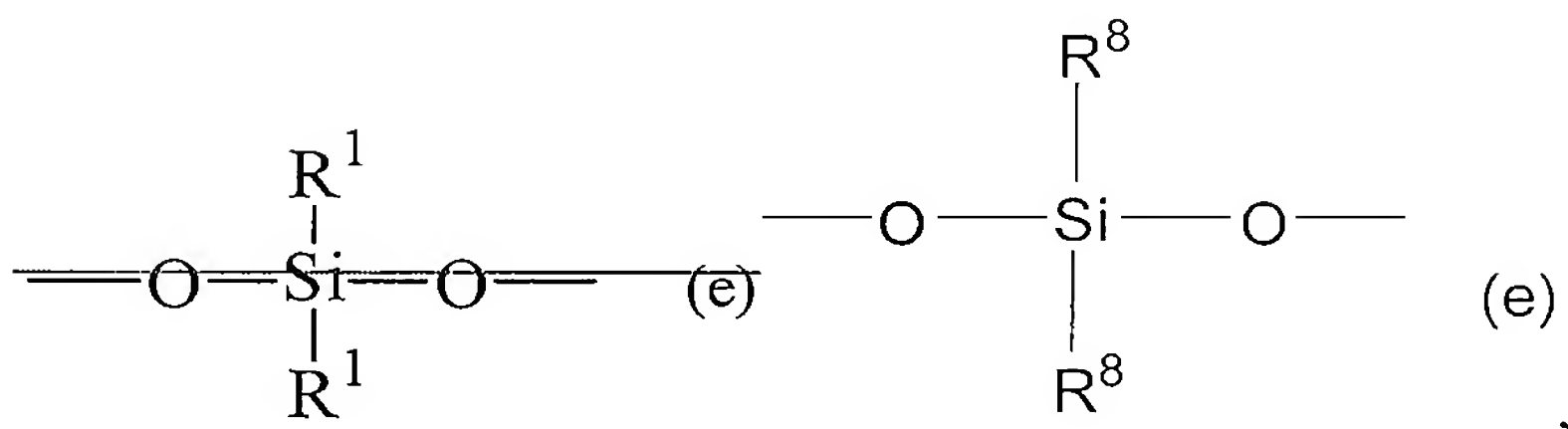
{wherein, R^1 - R^7 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R^1 - R^7 in the silicon-containing polymer may be the same, or different from, each other; and

X represents an epoxy group-containing monovalent organic group}.

14. (Currently Amended) The sealant epoxy-resin molding material according to Claim 13, wherein the silicon-containing polymer (F) has the following bond (e) additionally:

———[Formula 5]



{wherein, R^1 - R^8 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; and

the groups R^1 - R^8 in the silicon-containing polymer may be the same, as or different from, each other}.

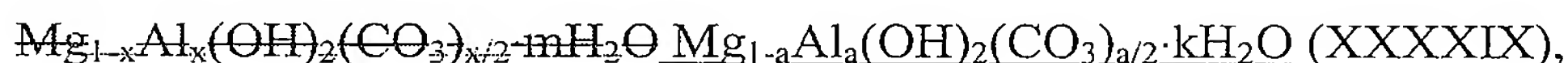
15. (Previously Presented) The sealant epoxy-resin molding material according to Claim 13, wherein the softening temperature of the silicon-containing polymer (F) is 40°C or higher and 120°C or lower.

16. (Currently Amended) The sealant epoxy-resin molding material according to Claim 13, wherein $\text{R}^1\text{-}\underline{\text{R}}^7$ in the silicon-containing polymer (F) is at least one of a substituted or unsubstituted phenyl group and a substituted or unsubstituted methyl group.

17. (Currently Amended) The sealant epoxy-resin molding material according to Claim 13, wherein the rate of substituted or unsubstituted phenyl groups having 1 to 12 carbon atoms in all groups $\underline{\text{R}}^7\text{R}^1$ in the silicon-containing polymer (F) is 60 to 100 mol %.

18. (Currently Amended) The sealant epoxy-resin molding material according to Claim 1, further comprising at least one of a compound (G) represented by Compositional Formula (XXXXIX) and a compound (H) represented by the following Compositional Formula (XXXXXXIX):

(Formula 6)



wherein $\{0 < \underline{a} \leq 0.5; \text{ and}$

\underline{k} is a positive number), and

(Formula 7)

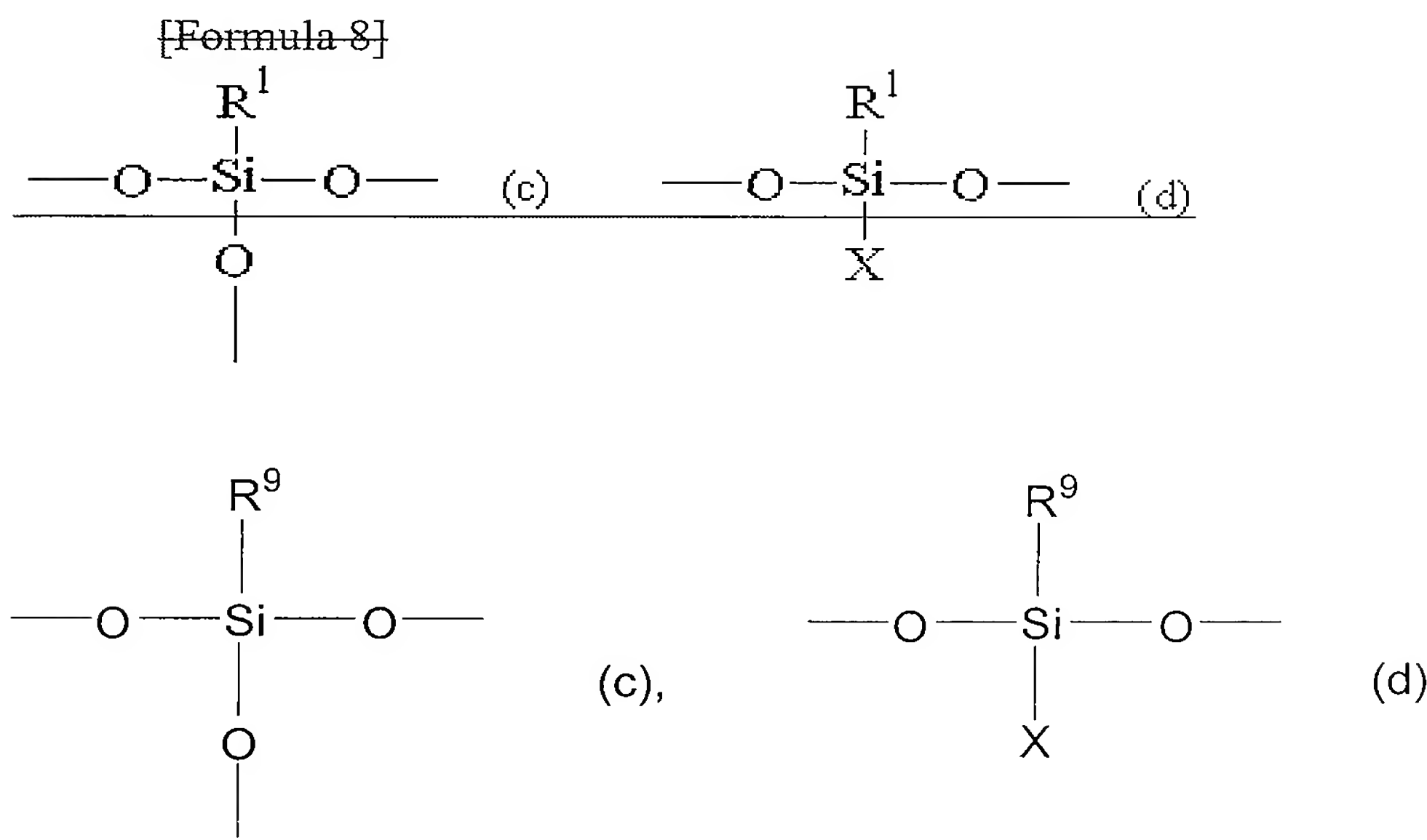


wherein $\{0.9 \leq \underline{b} \leq 1.1, 0.6 \leq y \leq 0.8, \text{ and } 0.2 \leq z \leq 0.4\}$.

19. (Previously Presented) An electronic component device, comprising an element sealed with the sealant epoxy-resin molding material according to Claim 13.

20. (Previously Presented) The sealant epoxy-resin molding material according to Claim 6, further comprising a coupling agent (E).

21. (Currently Amended) The sealant epoxy-resin molding material according to Claim 20, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), ~~a terminal selected from R⁺, a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000.~~



a terminal selected from R⁹, a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

(wherein, R⁺ R⁹ represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R⁹ R⁺ in the silicon-containing polymer may be the same as, or different from, each other; and

X represents an epoxy group-containing monovalent organic group).

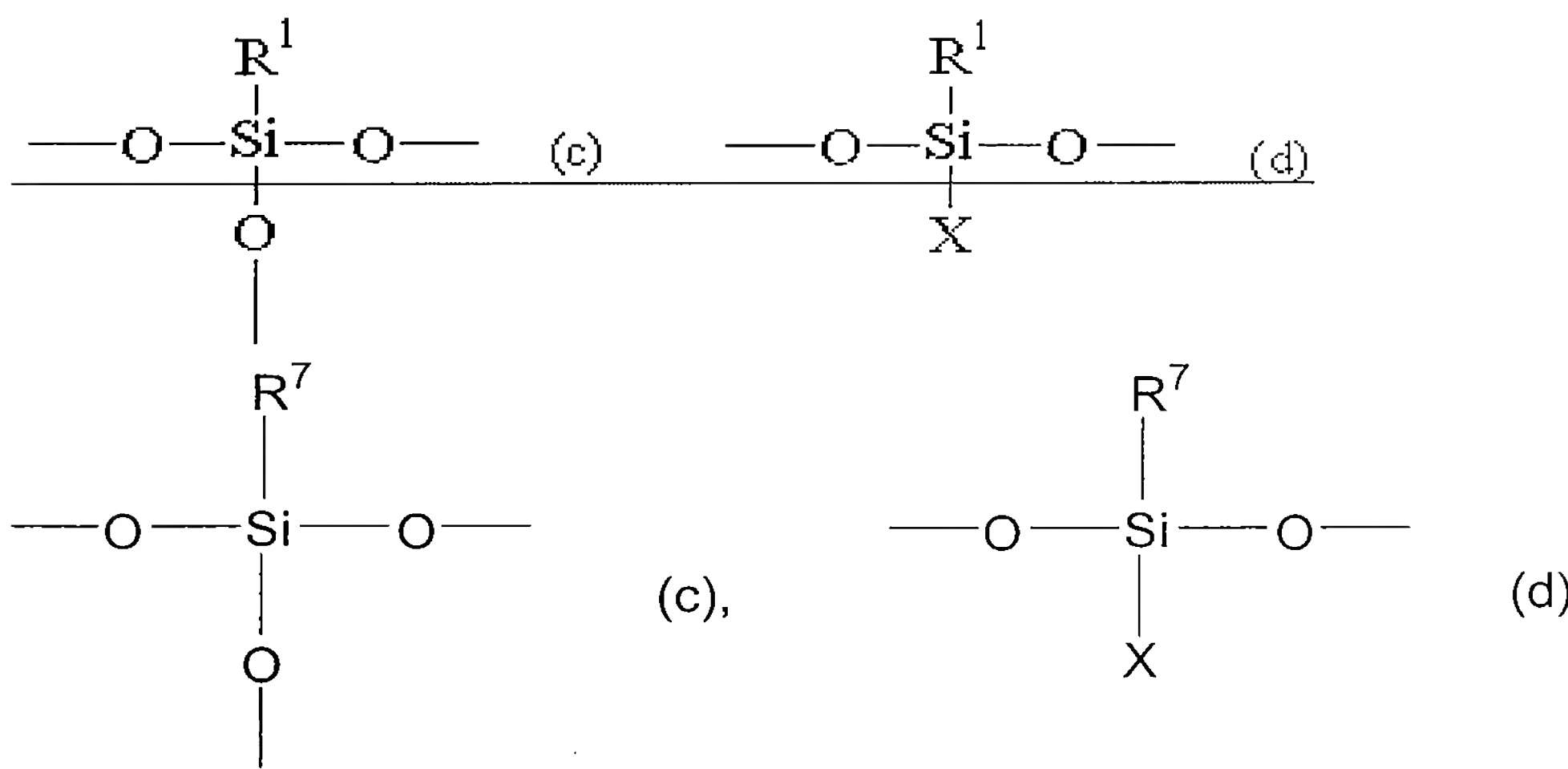
22. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising an inorganic filler (D).

23. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising a coupling agent (E).

24. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

25. (Currently Amended) The sealant epoxy-resin molding material according to Claim 3, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d), ~~a terminal selected from R^1 , a hydroxyl group and alkoxy groups, and an epoxy~~ equivalence of 500 to 4,000.

— [Formula 4]



a terminal selected from R^7 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

{wherein, R^7 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R^7 in the silicon-containing polymer may be the same as or different from each other; and

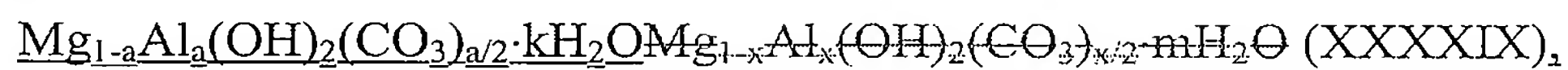
X represents an epoxy group-containing monovalent organic group}.

26. (Currently Amended) The sealant epoxy-resin molding material according to Claim 3, further comprising at least one of a compound (G) represented by Compositional

Formula (XXXXIX) and a compound (H) represented by the following Compositional

Formula (XXXXIX):

(Formula-6)



wherein $0 < a \leq 0.5$; and

m is a positive number), and

(Formula-7)



wherein $0.9 \leq b \leq 1.1$, $0.6 \leq y \leq 0.8$, and $0.2 \leq z \leq 0.4$.